



Note 1. Demarcation between AGND and DGND on motherboard connectors. For FM, positioned between pins 55, 56, 57 and 58, 59, 60. (PM position was between pins 94, 95, 96 and 97, 98, 99.)

Note 2. At each CCD there is galvanic isolation between invar mounts and substrate, and approx 1nF capacitance. Provision is made on the analogue card to bond AGND to the ROE box, as alternative to the bond point if required.

Solar B EIS Camera Grounding Scheme - FM
Phil Thomas MSSL-UCL July 2002